

Abstract

Encapsulated Electronic Component And Production Method

5 The present invention relates to an encapsulated component that includes a carrier substrate and at least one chip positioned on the top of the carrier substrate and electrically connected to it by means of electrically conductive connections. The encapsulation of the chip is accomplished with a seal or dielectric layer. As a result of differing coefficients of expansion of the seal or dielectric layer and the electrically conductive connections, with

10 changing temperatures stresses occur in the electrically conductive connections, which can lead to cracks, breaks and even to interruption of the electrically conductive connections. To mechanically relieve the electrically conductive connections of stresses from changing temperatures (in particular under extreme thermal loads), it is proposed that the carrier substrate be provided with a support element that encircles the chip, which serves to

15 support the seal or dielectric layer, and/or that the material and the arrangement of the encapsulation be selected accordingly.

Figure 1